

## **AMENDMENTS TO THE CLAIMS**

The following listing of claims will replace all prior versions and listings of claims in the application.

### **LISTING OF CLAIMS**

1. - 8. (Cancelled)

9. (Currently Amended) A semiconductor device mounting structure including a semiconductor device having an electrode and a substrate having a wiring terminal that is conductively connected to the electrode, wherein

a width of the wiring terminal is smaller than a width of the electrode;

a recessed portion formed in a center portion of the electrode, the recessed portion is constituted by a dimension corresponding to the width of the wiring terminal; and

the one of the electrode and the wiring terminal is embedded in a surface of the other of the electrode and the wiring terminal;

wherein the electrode further comprises a material having a higher hardness than a hardness of the wiring terminal.

10. – 23. (Cancelled)